FCAB21350L1

# **Panasonic**

## FCAB21350L1

#### Gate resistor installed Dual N-channel MOS FET

For lithium-ion secondary battery protection circuits

#### ■ Features

- Low source-source ON resistance:Rss(on) typ. = 2.2 mΩ(VGS = 3.8 V)
- · CSP(Chip Size Package)
- · RoHS compliant (EU RoHS / MSL:Level 1 compliant)
- Marking Symbol: 3M

#### ■ Packaging

Embossed type (Thermo-compression sealing): 1 000 pcs / reel (standard)

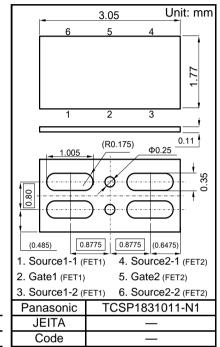
■ Absolute Maximum Ratings Ta = 25 °C

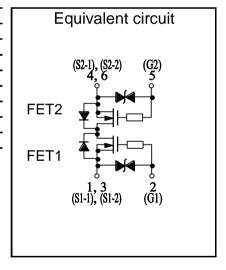
Parameter		Symbol	Rating	Unit	
Source-source Voltage		VSS	12	V	
Gate-source Voltage		VGS	±8	V	
Source Current	DC *1	IS1	12	Α	
	DC *2	IS2	27	Α	
	Pulse *3	ISp	120	Α	
Total Power Dissipation	DC *1	PD1	0.45	W	
Total Fower Dissipation	DC *2	PD2	2.1	W	
Channel Temperature		Tch	150	°C	
Storage Temperature Range		Tstg	-55 to +150	°C	
Thermal Resistance (ch-a)	DC <sup>*1</sup>	Rth1	278	°C/W	
	DC *2	Rth2	59	°C/W	

- Note \*1 Mounted on FR4 board (  $25.4~\text{mm} \times 25.4~\text{mm} \times t1.0~\text{mm}$  ) using the minimum recommended pad size ( $36\mu\text{m}$  Copper ).
  - \*2 Mounted on Ceramic substrate (70 mm  $\times$  70 mm  $\times$  t1.0 mm).
  - \*3  $t = 10 \mu s$ , Duty Cycle  $\leq 1 \%$

Established: 2015-10-23

Revised





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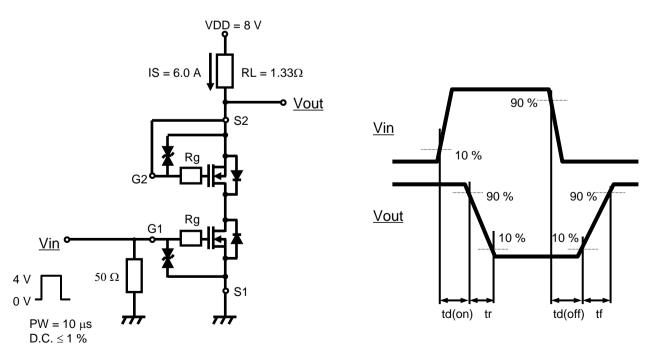
#### ■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit	
Source-source Breakdown Voltage	VSSS	IS = 1 mA, VGS = 0 V	12			V	
Zero Gate Voltage Source Current	ISSS	VSS = 12 V, VGS = 0 V			1.0	μΑ	
Gate-source Leakage Current	IGSS	$VGS = \pm 8 \text{ V}, VSS = 0 \text{ V}$			±10		
	1000	$VGS = \pm 5 V$ , $VSS = 0 V$			±1.0	μΑ	
Gate-source Threshold Voltage	Vth	IS = 1.41 mA, VSS = 10 V	0.35	0.90	1.40	V	
Source-source On-state Resistance	RSS(on)1	IS = 6.0 A, VGS = 4.5 V	1.55	2.1	2.75	mΩ	
	RSS(on)2	IS = 6.0 A, VGS = 3.8 V	1.6	2.2	2.85		
	RSS(on)3	IS = 6.0 A, VGS = 3.1 V	1.65	2.4	3.95		
	RSS(on)4	IS = 6.0 A, VGS = 2.5 V	1.9	3.1	6.1		
Body Diode Forward Voltage	VF(s-s)	IF = 6.0 A, VGS = 0 V		0.8	1.2	V	
Input Capacitance *1	Ciss			4650		pF	
Output Capacitance *1	Coss	VSS = 10 V, VGS = 0 V, f = 1 KHz		580			
Reverse Transfer Capacitance *1	Crss			530			
Turn-on delay Time *1,*2	td(on)	VDD = 8 V, VGS = 0 to 4.0 V		1.2			
Rise Time *1,*2	tr	IS = 6.0 A		2.3		μS	
Turn-off delay Time *1,*2	td(off)	VDD = 8 V, VGS = 4.0 to 0 V		9		μS	
Fall Time *1,*2	tf	IS = 6.0 A		5.0			
Total Gate Charge *1	Qg	VDD = 8 V		43			
Gate-source Charge *1	Qgs	VGS = 0 to 4.0 V,	•	10		nC	
Gate-drain Charge *1	Qgd	IS = 6.0 A		10			

Note Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

- \*1 Guaranteed by design, not subject to production testing
- \*2 Measurement circuit for Turn-on Delay Time / Rise Time / Turn-off Delay Time / Fall Time

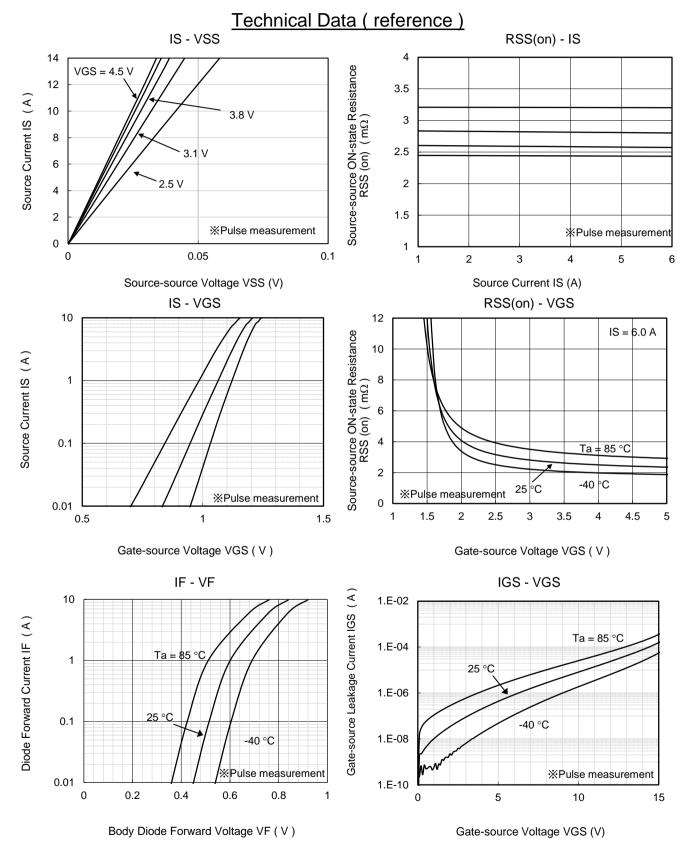
Note2: Measurement circuit



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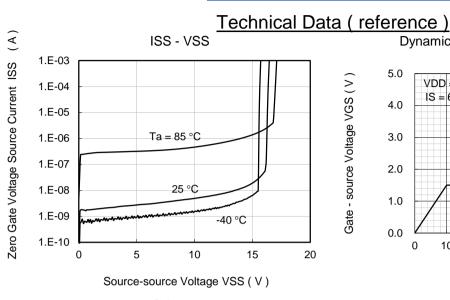
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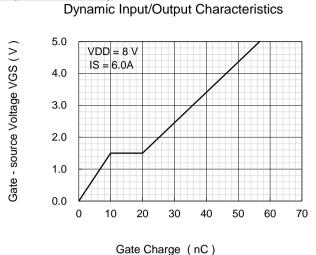
## **Panasonic**

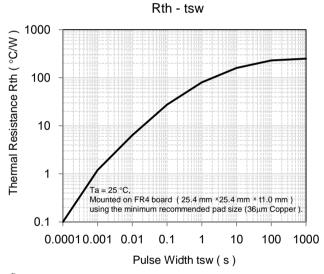


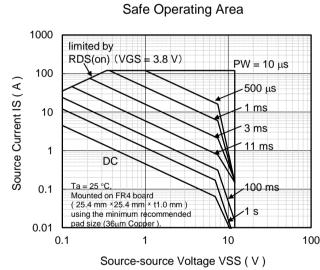
## FCAB21350L1

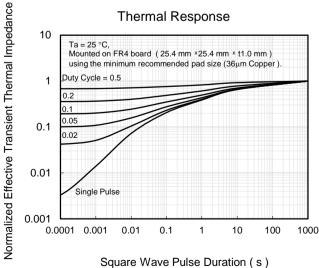
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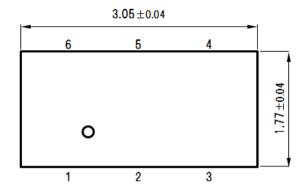
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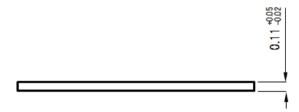
MOS FET

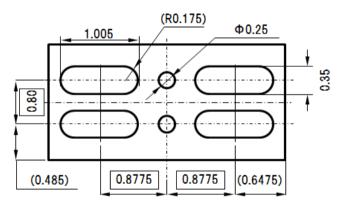
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#### ■ Outline (TCSP1831011-N1)

Unit: mm

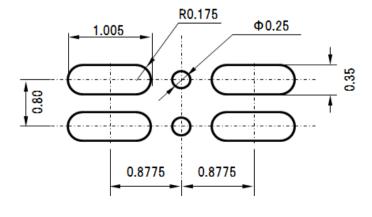






#### ■ Land Pattern (Reference)

Unit: mm



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